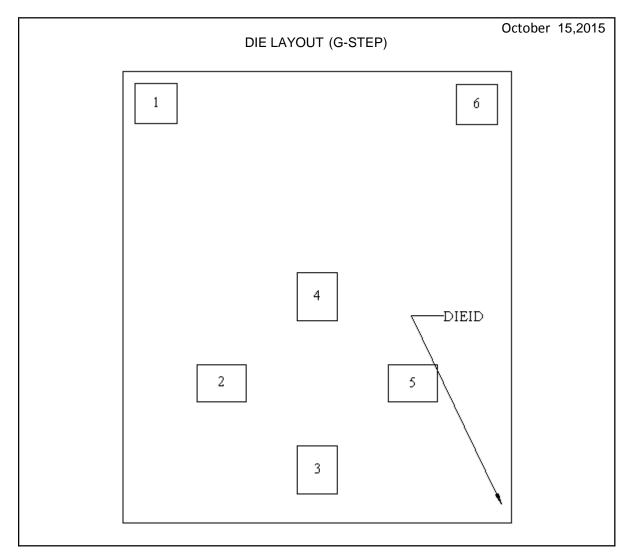


LM317A-MDC -MWC 3-TERMINAL ADJUSTABLE REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information		
Physical Die Identification	LM117G	Bond Pad Opening Size (min)	199µm x 193µm	
Die Step	G	Bond Pad Metalization	0.5%COPPER_BAL. ALUMINUM	
Phys	Physical Attributes		VOM NITRIDE	
Wafer Diameter	200mm	Back Side Metal	TITANIUM_NICKLE_SILVER BACKED	
Die Size (Drawn)	1880µm x 2184µm 74.0mils x 86.0mils	Back Side Connection	Vout	
Thickness	330µm Nominal			
Min Pitch	461µm Nominal			

Special Assembly Requirements

Note: Actual die size is rounded to the nearest micron.



DPBU Die Datasheet

LM317A MDC MWC 3-TERMINAL ADJUSTABLE REGULATOR

	Die Bond Pad Coordinate Locations (G -Step)					
(Referenced	(Referenced to die center, coordinates in μ m) NC = No Connection, N.U. = Not Used					
SIGNAL	PAD#	X/Y COO	DRDINATES	F	PAD SI	IZE
NAME	NUMBER	Х	Y	Х		<u>Y</u>
ADJ	1	-778	933	199	х	193
OUTPUT	2	-461	-418	240	Х	178
INPUT	3	1	-836	193	Х	234
INPUT	4	1	-1	193	Х	233
OUTPUT	5	463	-419	238	х	176
OUTPUT	6	774	932	199	х	193



LM317A MDC MWC 3-TERMINAL ADJUSTABLE REGULATOR

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